

Title (en)
EMBOSSING METHOD FOR EMBOSSING MICROSTRUCTURES OR NANOSTRUCTURES

Title (de)
PRÄGEVERFAHREN ZUM PRÄGEN VON MIKRO- ODER NANOSTRUKTUREN

Title (fr)
PROCÉDÉ D'ESTAMPAGE DE MICROSTRUCTURES OU DE NANOSTRUCTURES

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Application
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Abstract (en)
[origin: WO2017088964A2] The invention relates to a method for embossing structures with dimensions in the micrometer or nanometer range in a layer of varnish. The layer of varnish is applied to one side of a film web and can be hardened by means of ultraviolet radiation. The film web is located in the conveying direction initially on one side, on which the layer of varnish which is yet to harden is applied, pressed through a presser on a embossing cylinder on which surface the structures which are to be stamped in the micrometer or nanometer region are arranged. This forms the structures in the micrometer range or in the nanometer range in the layer of varnish. Subsequently, the layer of varnish is hardened by ultraviolet radiation of a source for ultraviolet radiation. According to the invention, the film web is guided to the stamping cylinder from above or at least obliquely from above.

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